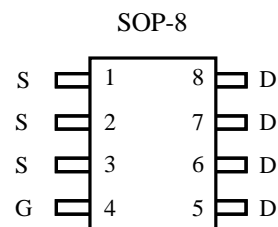


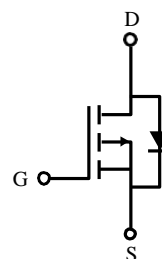
N-Channel High Density Trench MOSFET

Features:

- Super high dense cell trench design for low RDS(on).
- Rugged and reliable.
- Surface Mount package.



PRODUCT SUMMARY		
$V_{(BR)DSS}$	$R_{DS(on)}$ (m Ω) Max	I_D
60V	39 @ $V_{GS}=10V$	8A
	46 @ $V_{GS}=4.5V$	6A



ABSOLUTE MAXIMUM RATINGS (TA = 25 °C unless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V_{DS}	60	V	
Gate-Source Voltage	V_{GS}	± 20	V	
Drain Current-Continuousa $T_C = 25\text{ }^\circ\text{C}$	I_D	10	A	
	I_{DM}	40		
Maximum Power Dissipation (Note 1)	P_D	$T_A=25\text{ }^\circ\text{C}$	1.7	W
		$T_A=75\text{ }^\circ\text{C}$	1	
Operating Junction and Storage Temperature Range	T_J, T_{STG}	- 55 to 150	$^\circ\text{C}$	

THERMAL CHARACTERISTICS

Thermal Resistance, Junction-to-Ambient (Note 1)	R_{thJA}	48	$^\circ\text{C/W}$
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Note:

1. Surface Mounted on FR4 Board , $t \leq 10\text{sec}$.

ELECTRICAL CHARACTERISTICS (TA = 25 °C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0V, I_D = 250\mu A$	60			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 48V, V_{GS} = 0V$			1	μA
Gate-Body Leakage	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$			± 100	nA
ON CHARACTERISTICS (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1	1.7	2.5	V
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 8A$		33	39	m Ω
		$V_{GS} = 4.5V, I_D = 6A$		36	46	m Ω
Forward Transconductance	gfs	$V_{DS} = 5V, I_D = 5A$		10		S
DYNAMIC CHARACTERISTICS (Note 4)						
Input Capacitance	C_{ISS}	$V_{DS} = 30V, V_{GS} = 0V$ $f = 1.0MHz$		1112		pF
Output Capacitance	C_{OSS}			63		pF
Reverse Transfer Capacitance	C_{RSS}			42		pF
SWITCHING CHARACTERISTICS (Note 4)						
Turn-On Delay Time	$t_{d(ON)}$	$V_{DS} = 30V, I_D = 1A, V_{GS} = 10V$ $R_{GS} = 6\Omega, R_L = 15\Omega$		6.1		nS
Rise Time	tr			23		nS
Turn-Off Delay Time	$t_{d(OFF)}$			43		nS
Fall Time	tf			22		nS
Total Gate Charge	Qg	$V_{DS} = 30V, I_D = 8A$ $V_{GS} = 10V$		27		nC
Gate-Source Charge	Qgs			3.8		nC
Gate-Drain Charge	Qgd			4.7		nC
DRAIN-SOURCE DIODE CHARACTERISTICS						
Drain-Source Diode Forward Current (Note 1)	I_S			6		A
Diode Forward Voltage (Note 3)	V_{SD}	$V_{GS} = 0V, I_S = 1.0A$		0.77	1.1	V

Note:

- 3. Pulse Test Pulse width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
- 4. Guaranteed by design, not subject to production testing.

N-Channel High Density Trench MOSFET

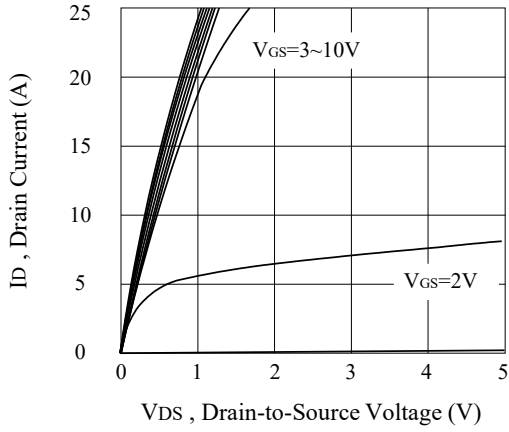


Figure 1. Output Characteristics

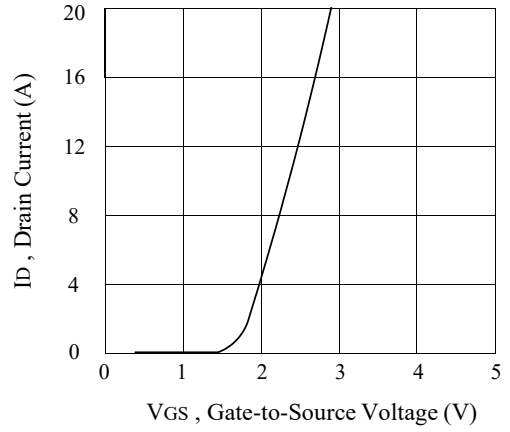


Figure 2. Transfer Characteristics

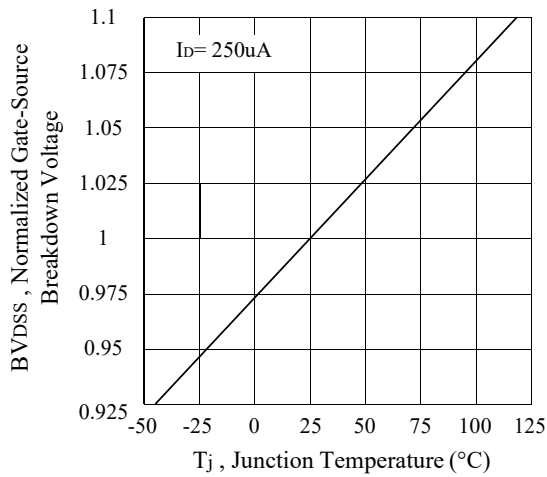


Figure 3. Breakdown Voltage Variation with Temperature

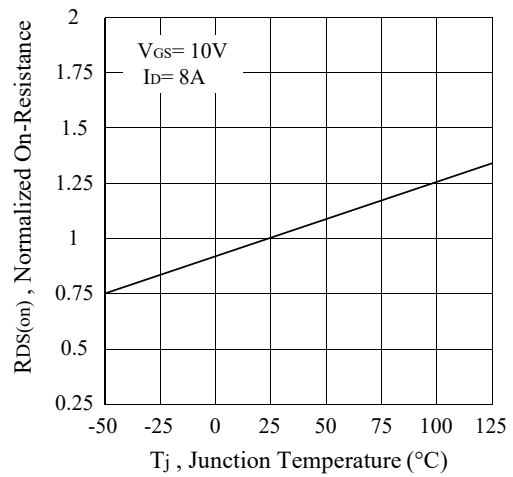


Figure 4. On-Resistance Variation with Temperature

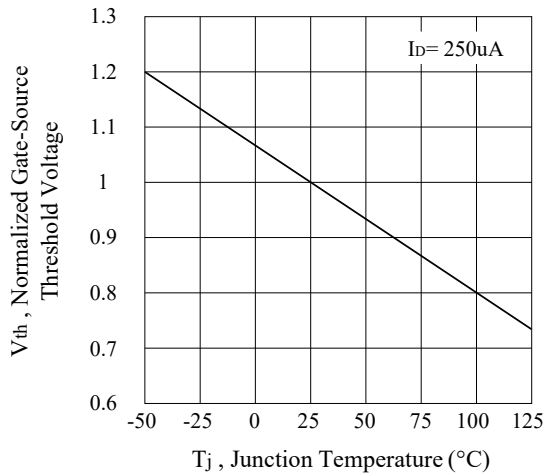


Figure 5. Gate Threshold Variation with Temperature

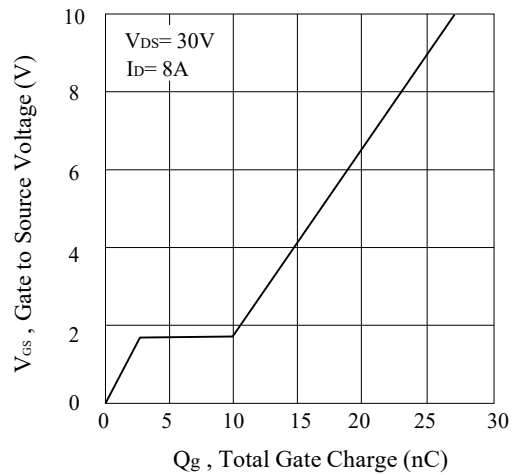


Figure 6. Gate Charge

N-Channel High Density Trench MOSFET

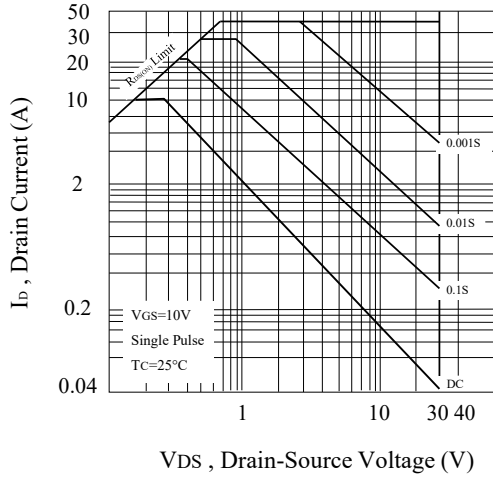


Figure 7. Maximum Safe Operating Area

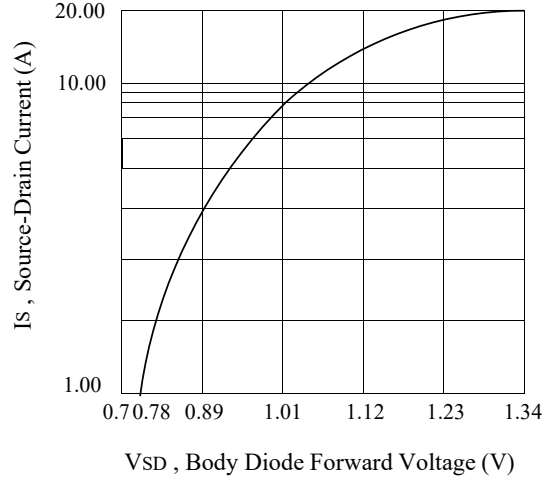


Figure 8. Body Diode Forward Voltage Variation with Source Current

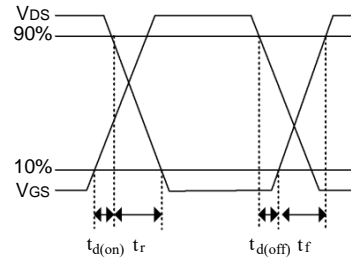
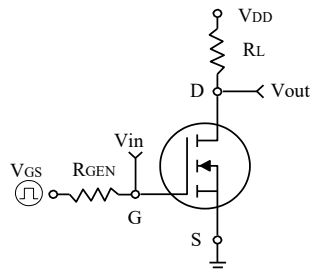


Figure 9. Switching Test Circuit and Switching Waveforms

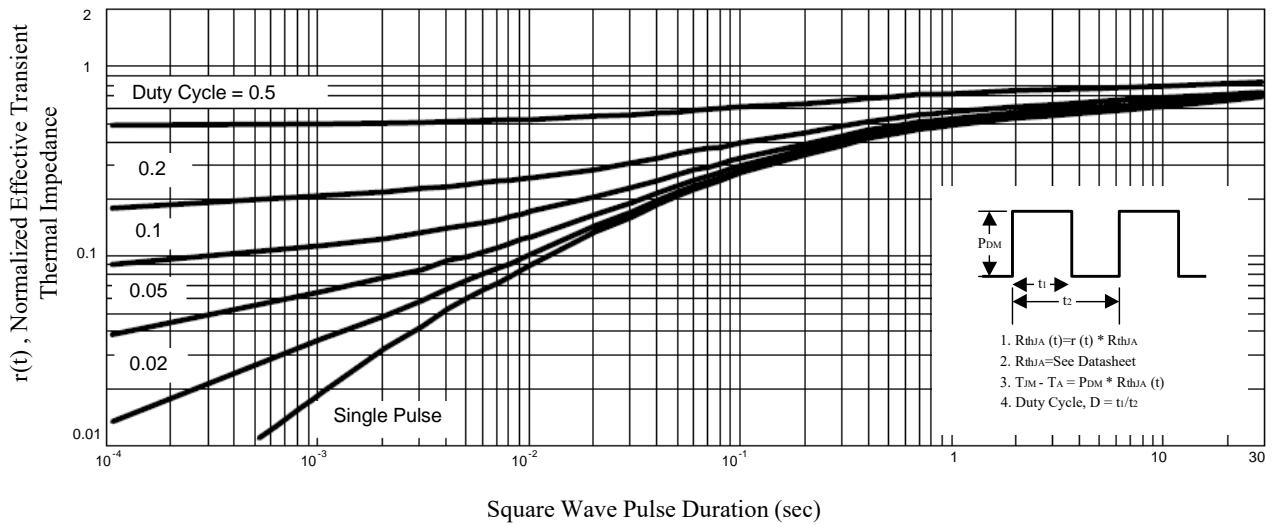


Figure 10. Normalized Thermal Transient Impedance Curve